

A Symposium on High-Performance Chips



*Stanford University,
Palo Alto, California*
August 20-22, 2006

Call for Contributions

AUTHOR'S SCHEDULE

Deadline for submissions: **March 25, 2006**

Notification of acceptance: **April 30, 2006**

Deadline for final version: **July 20, 2006**

AREAS OF INTEREST:

- **Microprocessors**
- **Systems-on-chip**
- **Embedded processors**
- **Chipset chips**
- **Digital signal processors**
- **Application-specific processors**
- **Communication/networking chips**
- **Wireless LAN/Wireless WAN chips**
- **Network/security processors**
- **Chips built from FPGAs**
- **Compiler technology**
- **Novel chips: quantum computing, nano-structures, micro-arrays**
- **Low-power chips/Dynamic power management**
- **Graphics/Multimedia/Game processors/Display technology**
- **Advanced semiconductor process technology**
- **Reconfigurable chips/processors**
- **Operating system/chip interaction**
- **Advanced packaging technology**
- **Reliability and design for test**
- **Performance evaluation**

AUTHOR INFORMATION AND FORMAT

Presentations at HOT Chips are in the form of 30-minute talks. Presentation slides will be published in the HOT Chips Proceedings. Participants are not required to submit written papers, but a select group will be invited to submit a paper for inclusion in a special issue of IEEE Micro.

Submissions must consist of a title, extended abstract (two pages maximum.), and the presenter's contact information (name, affiliation, job title, address, phone(s), fax, and email). Please indicate whether you have submitted, intend to submit, or have already presented or published a similar or overlapping submission to another conference or journal. Also indicate if you would like the submission to be held confidential; we do our best to maintain confidentiality if requested.

Submissions should be in plain ASCII text, pasted into the message; do not submit .doc files, .txt files, MIME'd email, any attachments or other formats. Submissions containing figures may be submitted in pdf, but plain ASCII text is strongly preferred.

Submissions are evaluated by the Program Committee on the basis of performance of the device(s), degree of innovation, use of advanced technology, potential market significance, and anticipated interest to the audience. Research and software contributions will be evaluated with similar criteria.

Please mail your submissions in plain ASCII text (in the message, not as an attachment!) by **March 25, 2006** to: hotchipssubmit@cs.berkeley.edu Authors will be notified as to acceptance by **April 30, 2006**.

Send questions relating to the program to the program chairs at: hotpcchairs@cs.berkeley.edu and questions relating to conference operation or organization to the general chair, Yusuf Abdulghani, at: hotgeneralchair@cs.berkeley.edu.

Sponsored by the Technical Committee on Microprocessors and Microcomputers of the IEEE Computer Society



Program Committee Co-Chairs
Prof. John Kubiatowicz, UC Berkeley
Howard Sachs, Telairity Semiconductor



Check the HOT CHIPS 18 web page for updates: <http://www.hotchips.org>



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Call for Papers

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18
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